

Title (en)
MEMS COMPONENTS AND METHOD FOR MANUFACTURING SAME

Title (de)
MEMS-BAUTEILE UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
COMPOSANTS MEMS ET LEURS PROCÉDÉS DE FABRICATION

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Application
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Abstract (en)
[origin: WO2007089204A1] The invention relates to a method for making a MEMS device having connectors for interconnecting components in the MEMS device. The method comprises applying a sacrificial material layer on a first substrate wafer, the thickness of the sacrificial layer essentially defining the length of the connectors. Connectors made of electrically conducting and/ or mechanically rigid material are provided and embedded in the sacrificial material layer. Components are provided on top of the sacrificial layer by 3D integration with wafer bonding, to connect the components to the connectors. It also relates to a MEMS device made by 3D integration with wafer bonding comprising first and a second components interconnected by connectors having a length of > 4µm. The components can comprise integrated circuits.

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• No further relevant documents disclosed
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